

<b>PCN Number:</b>	20210205000.1	<b>PCN Date:</b>	May 11, 2021
<b>Title:</b>	Qualification of UTL3 as an additional assembly site for select Devices		
<b>Customer Contact:</b>	<a href="#">PCN Manager</a>	<b>Dept:</b>	Quality Services
<b>Proposed 1<sup>st</sup> Ship Date:</b>	Aug. 11, 2021	<b>Estimated Sample Availability:</b>	Date provided at sample request
<b>Change Type:</b>			
<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design
<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
		<input type="checkbox"/>	Wafer Bump Site
		<input type="checkbox"/>	Wafer Bump Material
		<input type="checkbox"/>	Wafer Bump Process
		<input type="checkbox"/>	Wafer Fab Site
		<input type="checkbox"/>	Wafer Fab Materials
		<input type="checkbox"/>	Wafer Fab Process
<b>PCN Details</b>			
<b>Description of Change:</b>			
Texas Instruments Incorporated is announcing the qualification of UTL3 as an alternate Assembly site for devices listed below in the product affected section. There are no construction differences between the two sites			
<b>Reason for Change:</b>			
Supply continuity			
<b>Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):</b>			
None			
<b>Anticipated impact on Material Declaration</b>			
<input checked="" type="checkbox"/>	No Impact to the Material Declaration	<input type="checkbox"/>	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained at the site link below <a href="http://www.ti.com/quality/docs/materialcontentsearch.tsp">http://www.ti.com/quality/docs/materialcontentsearch.tsp</a>
<b>Changes to product identification resulting from this PCN:</b>			
<b>Assembly Site</b>	<b>Assembly Site Origin (22L)</b>	<b>Assembly Country Code (23L)</b>	<b>Assembly City</b>
UTL1	NSE	THA	Bangkok
<b>UTL3</b>	<b>UT3</b>	<b>THA</b>	<b>Bangpakong</b>
Sample product shipping label (not actual product label)			
<b>Product Affected:</b>			
74AVC4T245RSVRG4	SN74LVC1G07DRYRG4	TPS3898PDRYR	TPS73733DRVR
74AVC4T774RSVR-NT	SN74LVC1G126DRYR	TPS60151DRVR	TPS78001DRVR
74AVC4T774RSVRG4	SN74LVC1G175DRYR	TPS61240DRVR	TPS78001DRVRG4

74AVCH4T245RSVRG4	SN74LVC1G3157DRYR	TPS622311DRYR	TPS780180300DRVR
74LVC1G3157DRYRG4	TCA6424ARGJR	TPS622311DRYT	TPS78101DRVR
ADS1013IRUGR	TCA6507RUER	TPS622314DRYR	TPS78227DRVR
ADS1014IRUGR	TLA2021IRUGR	TPS62231DRYR	TPS78227DRVT
ADS1015IRUGR	TLA2022IRUGR	TPS62232DRYR	TPS79901DRVR
ADS1015IRUGT	TLA2024IRUGR	TPS62232DRYT	TPS79901DRVRG4
ADS1018IRUGR	TLA2024IRUGT	TPS62240DRVR	TPS79912DRVR
ADS1113IRUGT	TLV342IRUGR	TPS62240DRVRG4	TPS79918DRVR
ADS1114IRUGR	TLV70018DSER	TPS62240DRVT	TPS79918DRVRG4
ADS1115IRUGR	TLV7101828DSER	TPS62242DRVR	TPS79918DRVT
ADS1115IRUGT	TLV7111533DDSER	TPS62242DRVRG4	TPS79927DRVR
ADS1118IRUGR	TMP451AIDQFR	TPS62243DRVR	TPS79928DRVR
HPA00719RSVR	TPD2E001DRYR	TPS62250DRVR	TPS79928DRVT
INA199A2RSWR	TPD2E001DRYRG4	TPS62261DRVT	TPS79933DRVR
INA199B1RSWR	TPD3E001DRYR	TPS62270DRVT	TPS79933DRVRG4
INA199B2RSWT	TPD3E001DRYRG4	TPS62291DRVR	TPS7A3701DRVR
INA199C3RSWR	TPD4E004DRYR	TPS62291DRVT	TPS7A3701DRVT
INA211B1RSWR	TPD4E004DRYRG4	TPS62293DRVR	TS3A24157RSER
INA211B1RSWT	TPD4S009DRYR	TPS62293DRVRG4	TS3A24157RSERG4
INA213A1RSWR	TPD4S012DRYR	TPS62560DRVR	TS3A44159RSVR
INA213B1RSWR	TPD6E001RSER	TPS62560DRVRG4	TS3A44159RSVRG4
INA216A1RSWR	TPD6E001RSERG4	TPS62560DRVT	TS3A4751RUCR
INA216A2RSWR	TPD6E004RSER	TPS62560DRVTG4	TS3A5017RSVR
INA216A2RSWT	TPS3421EGDRYR	TPS62562DRVR	TS3A5018RSVR
INA216A3RSWR	TPS3422EGDRYR	TPS62730DRYR	TS3USB221ERSER
INA216A4RSWR	TPS3422EGDRYT	TPS62730DRYT	TS3USB30RSWR
REG71050DRVR	TPS3710DSER	TPS62732DRYR	TS3USB31RSER
SN1203086RSWR	TPS3808G18DRVR	TPS62733DRYR	TS3USB31RSERG4
SN170670025DSER	TPS3808G33DRVR	TPS70918DRVR	TS3USB3200RSVR
SN74AVC2T245RSWR	TPS3895PDRYR	TPS71401DRVR	TS5A23157HRSER
SN74AVC4T245RSVR	TPS3896ADRYR	TPS715A01DRVR	TS5A23157RSER
SN74AVC4T774RSVR	TPS3897ADRYR	TPS715A33DRVR	TS5A23159RSER
SN74AVCH4T245RSVR	TPS3897ADRYT	TPS728100180DRVR	TS5A23159RSERG4
SN74LVC1G07DRYR	TPS3898ADRYR	TPS73701DRVR	

**Qualification Results**  
Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: CC2541F256RHAR	Qual Device: INA210AIRSWR	Qual Device: TPS22990DMLR
PC	Preconditioning	Level 1 - 260C	-	3/462/0	-
PC	Preconditioning	Level 2 - 260C	-	-	3/693/0
PC	Preconditioning	Level 3 - 260C	3/693/0	-	-
AC	Autoclave, 121C	96 Hours	3/230/0 <sup>1</sup>	3/231/0	3/231/0
BHAST	Biased HAST, 110C	264 Hours	3/230/0 <sup>2</sup>	-	3/231/0
ED	Electrical Characterization	Side by side	-	3/90/0	-
HTSL	High Temp. Storage Bake, 150C	1000 Hours	3/231/0	3/231/0	3/231/0
MSL	Moisture Sensitivity	Level 1 - 260C	-	3/36/0	-
MSL	Moisture Sensitivity (Cu Wire)	Level 2 - 260C	-	-	3/36/0
MSL	Moisture Sensitivity (Cu Wire)	Level 3 - 260C	3/36/0	-	-
SA	Salt Atmosphere	24 Hours	3/66/0	-	-
SD	Solderability, Pb-free	Steam age, 8 hours	3/66/0	3/66/0	3/66/0
TC	Temperature Cycle, -65C/150C	500 Cycles	3/231/0	3/231/0	3/231/0
MQ	Manufacturability (Assembly)	(per mfg. site specification)	3/Pass	3/Pass	3/Pass
BPCC	Bond Pad Cratering Check	Post Final Test	3/15/0	3/15/0	3/15/0
DS	Die Shear	Die	3/30/0	-	3/30/0
WBP	Wire Bond Pull	Wires	3/228/0	3/228/0	3/228/0
PD	Physical Dimensions	(per mechanical drawing)	3/15/0	3/15/0	3/15/0
VM	Visual / Mechanical	(per mfg. site specification)	3/36/0	3/36/0	3/36/0
XRAY	X-Ray	Top side only	3/15/0	3/15/0	3/15/0
YLD	FTY and Bin Summary	-	3/Pass	3/Pass	3/Pass

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable  
- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1000 Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours  
- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1000 Hours, and 170C/420 Hours  
- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Notes:

1. One device failed post-stress. Bin and failure analysis did not assign root cause to packaging issue, handling, or new factory. Discounted.
2. One device failed post-stress. Unit passed on retest. Discounted.

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

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